

FEATURES

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals

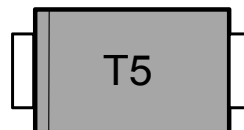


VOLTAGE RANGE

100 Volts

CURRENT

250 mA



MECHANICAL DATA

- **Case:** SOD-323 molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Laser band denotes cathode end

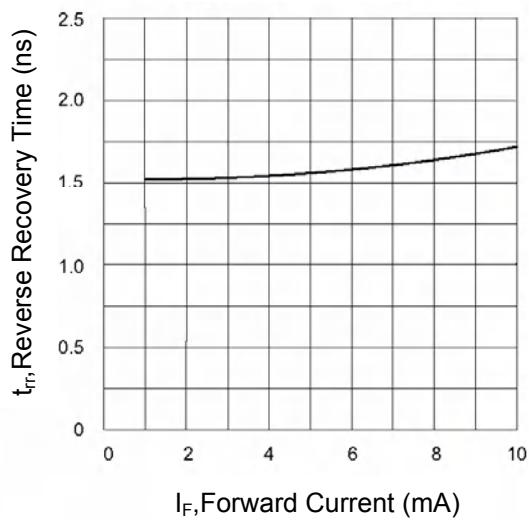
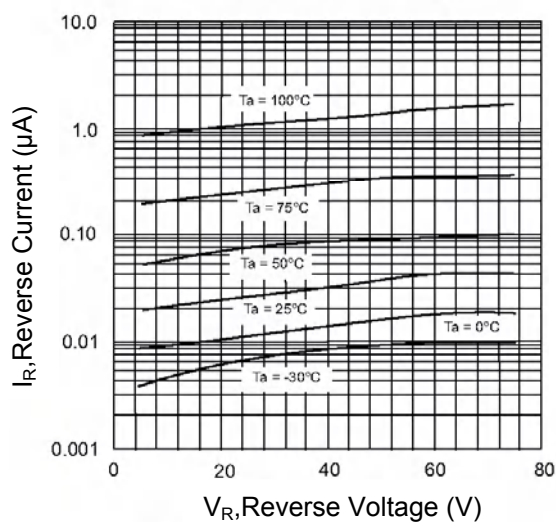
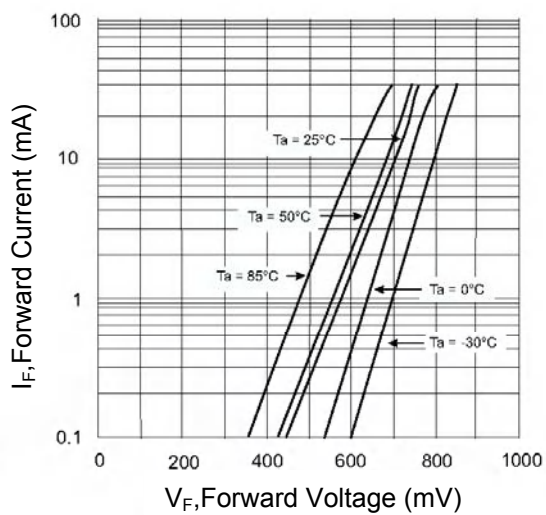
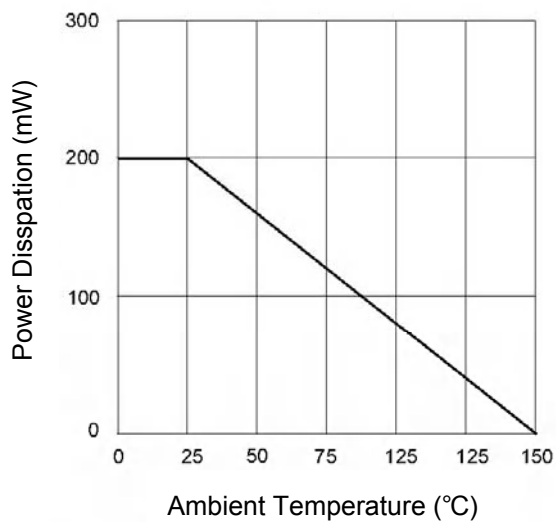
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	80	V
Average Rectified Forward Current	$I_{F(AV)}$	250	mA
Forward Continuous Current	I_{FM}	300	mA
Non-Repetitive Peak Forward Surge Current (at $t = 1 \mu s$)	I_{FSM}	0.5	A
Power Dissipation	P_d	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	- 65 to + 150	°C

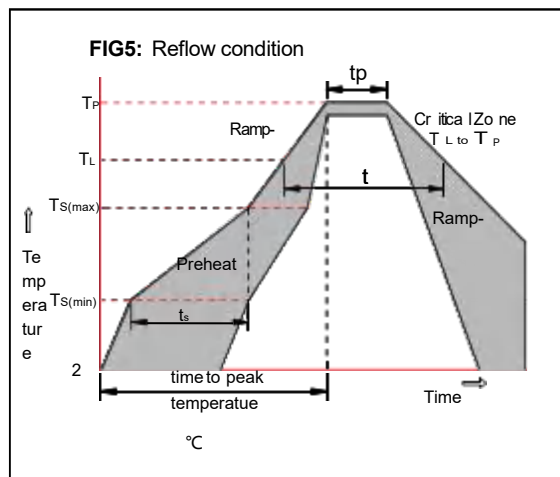
Parameter	Symbol	Min.	Max.	Unit
Forward Voltage at $I_F = 5 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 100 \text{ mA}$ at $I_F = 150 \text{ mA}$	V_F	0.62 - - -	0.72 0.855 1 1.25	V
Reverse Leakage Current at $V_R = 80 \text{ V}$ at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}, T_J = 150 \text{ °C}$ at $V_R = 25 \text{ V}, T_J = 150 \text{ °C}$	I_R	- - - -	100 25 50 30	nA nA μA μA
Reverse Breakdown Voltage at $I_R = 100 \mu A$	$V_{(BR)R}$	80	-	V
Total Capacitance at $V_R = 0.5 \text{ V}, f = 1 \text{ MHz}$	C_{tot}	-	4	pF
Reverse Recovery Time at $I_F = I_R = 10 \text{ mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$	t_{rr}	-	4	ns

RATING AND CHARACTERISTIC CURVES



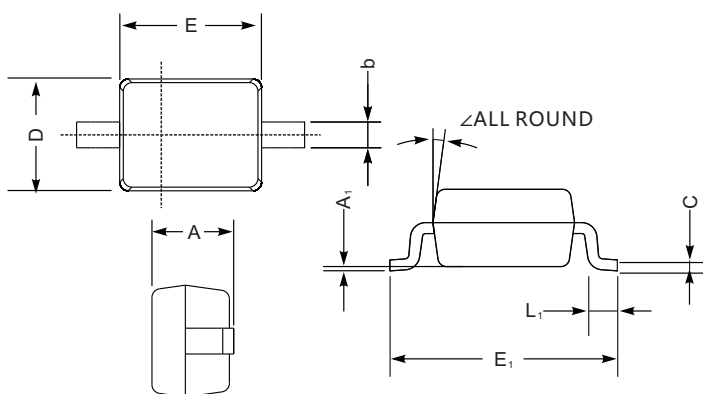
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



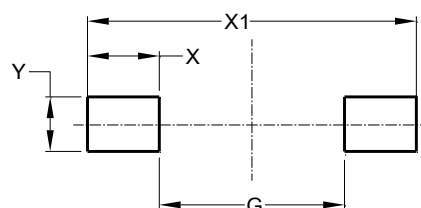
Package Dimensions & Suggested Pad Layout

SOD323



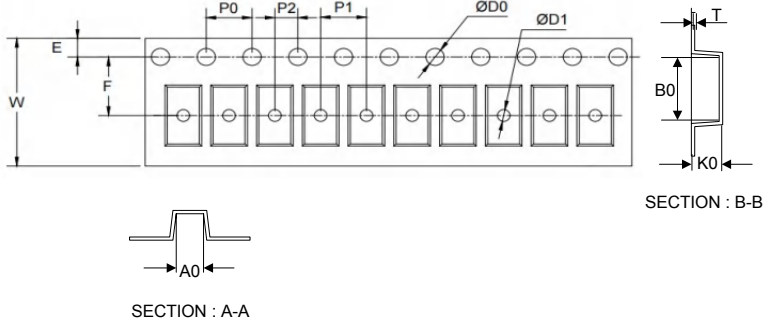
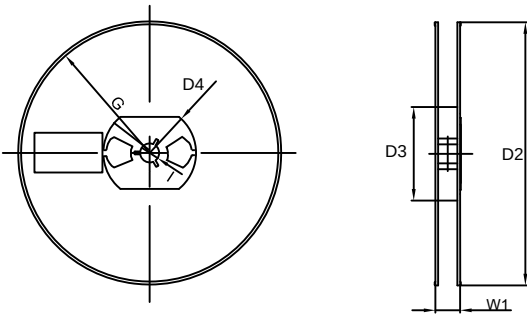
SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	1.00±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	2.00±0.20
		B0	3.25±0.20
		K0	1.35±0.20
		T	0.23±0.10
		D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
7" Reel		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	